

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
650V	41mΩ@10V	75A

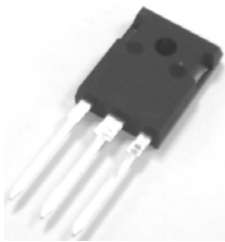
### Feature

- Low on-resistance and low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- New technology for high voltage device

### Application

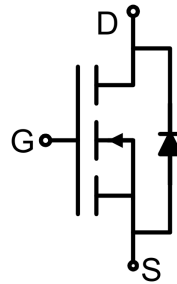
- Power factor correction
- Switched mode power supplies
- Uninterruptible Power Supply

### Package

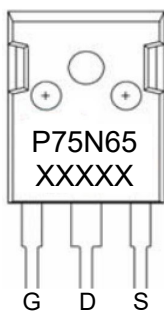


TO-247AB

### Circuit diagram



### Marking



### Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	±30	V
Continuous Drain Current	$I_D$	75	A
Drain Current-Continuous( $T_C = 100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	47	A
Pulsed Drain Current	$I_{DM}$	300	A
Power Dissipation	$P_D$	510	W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.245	$^\circ\text{C}/\text{W}$
Single pulse avalanche energy	$E_{AS}$	1936	mJ
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical characteristics ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 500\mu\text{A}$	650			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 650V, V_{GS} = 0V$			5	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 500\mu\text{A}$	2.5		4.5	V
Drain-source on-resistance <sup>1)</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 38A$		36	41	m $\Omega$
<b>Dynamic characteristics<sup>2)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 100V, V_{GS} = 0V, f = 1\text{MHz}$		7300		pF
Output Capacitance	$C_{oss}$			252		
Reverse Transfer Capacitance	$C_{rss}$			4		
Total Gate Charge	$Q_g$	$V_{DS} = 480V, V_{GS} = 10V, I_D = 75A$		116		nC
Gate-Source Charge	$Q_{gs}$			40		
Gate-Drain Charge	$Q_{gd}$			30		
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 380V, V_{GS} = 10V, I_D = 38A, R_{GEN} = 1.2\Omega$		27		nS
Turn-on rise time	$t_r$			22		
Turn-off delay time	$t_{d(off)}$			118		
Turn-off fall time	$t_f$			13		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current <sup>1)</sup>	$I_S$				75	A
Diode Forward voltage	$V_{DS}$	$V_{GS} = 0V, I_S = 75A$			1.3	V
Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}, I_F = 38A$		230		nS
Reverse Recovery Charge	$Q_{rr}$	$di/dt = 100A/\mu\text{s}^1)$		3		$\mu\text{C}$

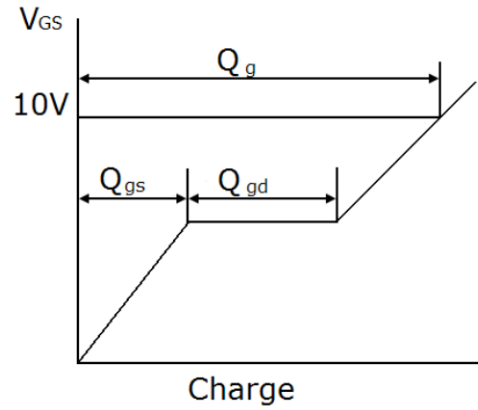
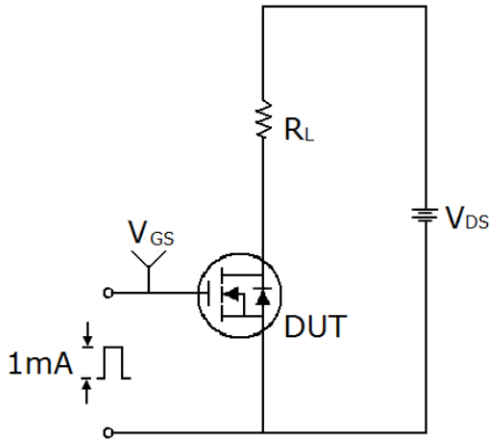
Notes:

1) Pulse Test: Pulse Width < 300 $\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

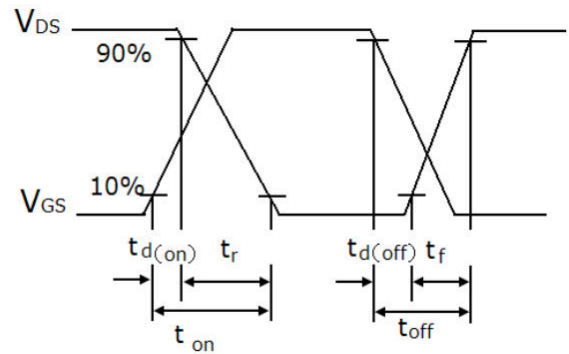
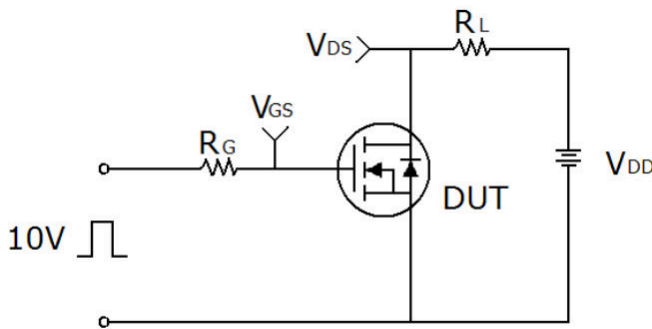
2) Guaranteed by design, not subject to production testing.

## Test Circuit

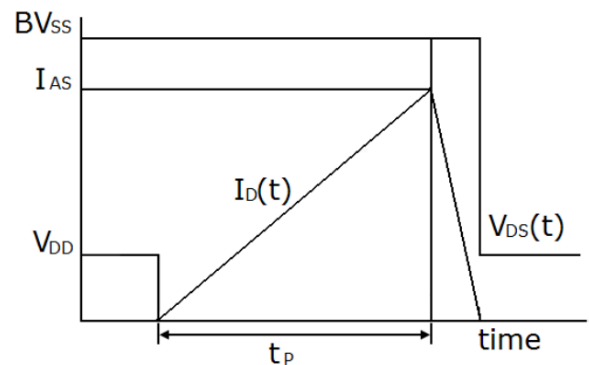
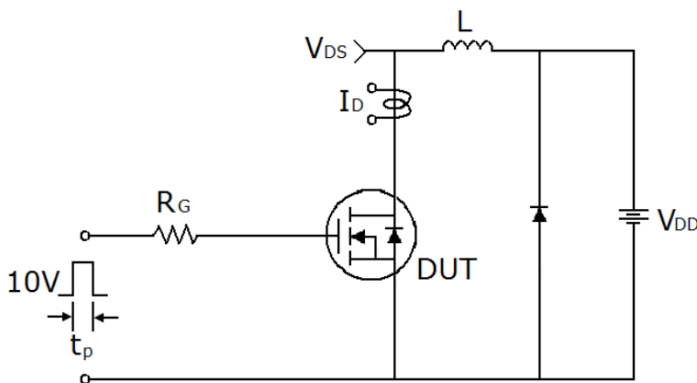
### 1) Gate charge test circuit & Waveform



### 2) Switch Time Test Circuit



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## Typical Characteristics

Figure1. Safe Operating Area

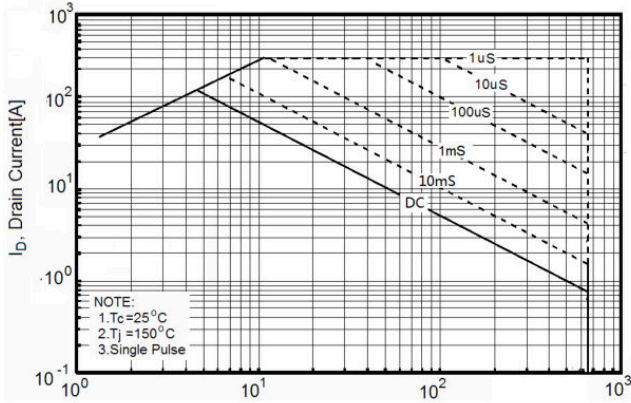


Figure2. Source-Drain Diode Forward Voltage

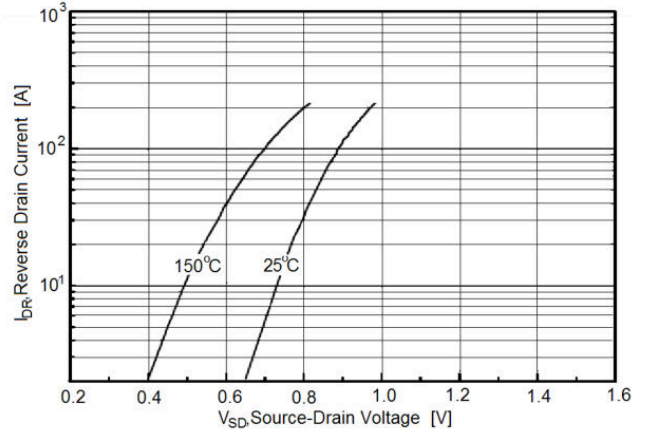


Figure3. Output Characteristics

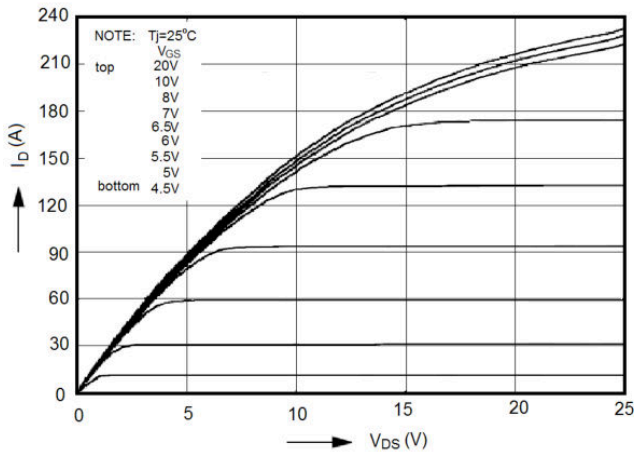


Figure4. Transfer Characteristics

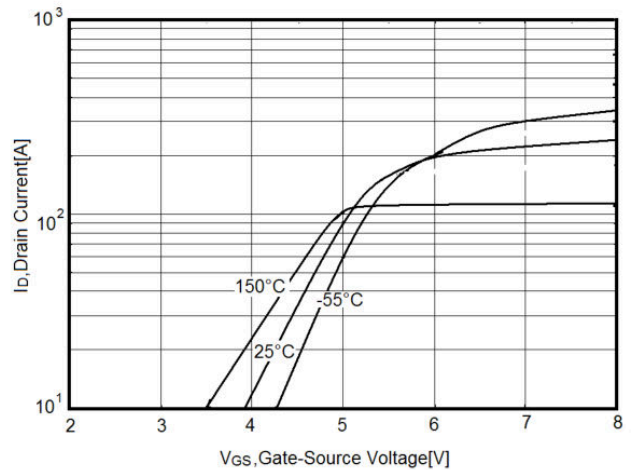


Figure5. Static drain-source on resistance

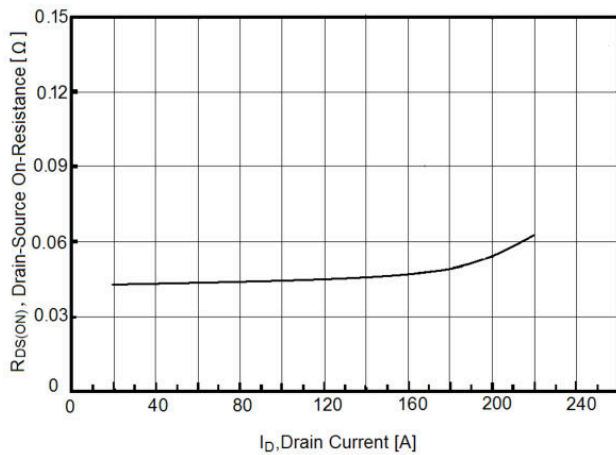
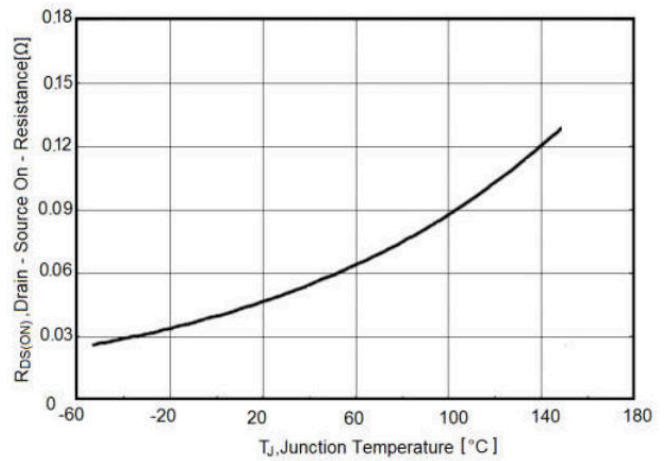


Figure6.  $R_{DS(ON)}$  vs Junction Temperature



## Typical Characteristics

Figure7.  $BV_{DSS}$  vs Junction Temperature

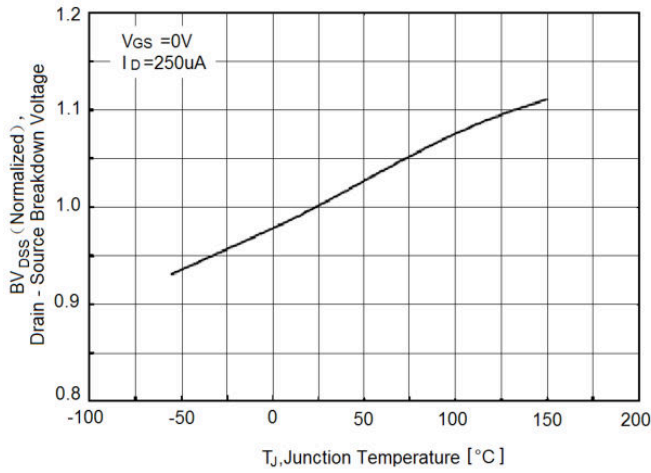
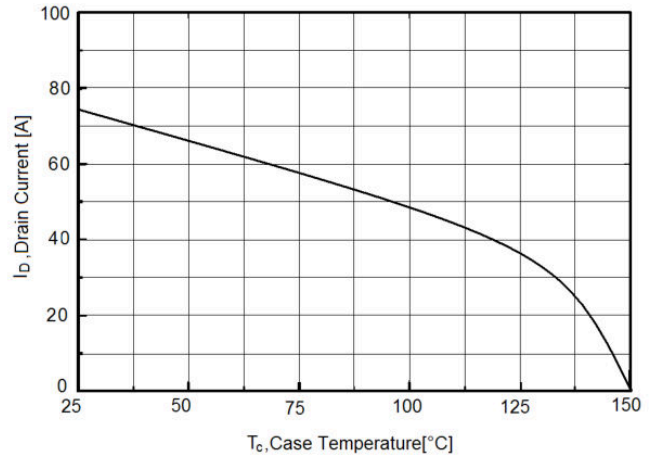
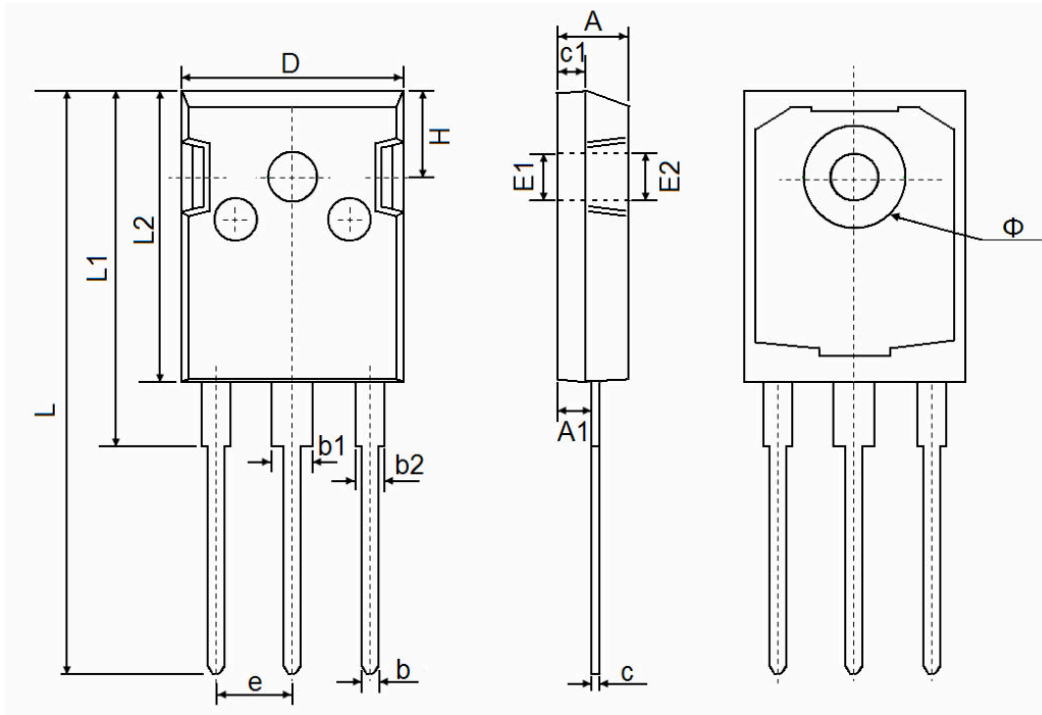


Figure8. Maximum  $I_D$  vs Junction Temperature



### TO-247AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
φ	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	